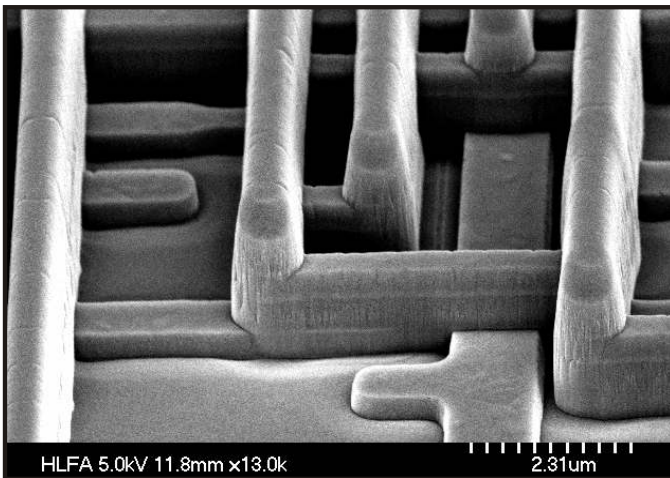
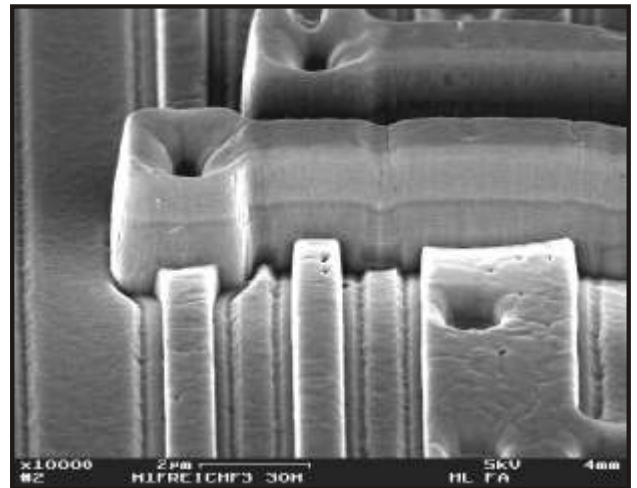
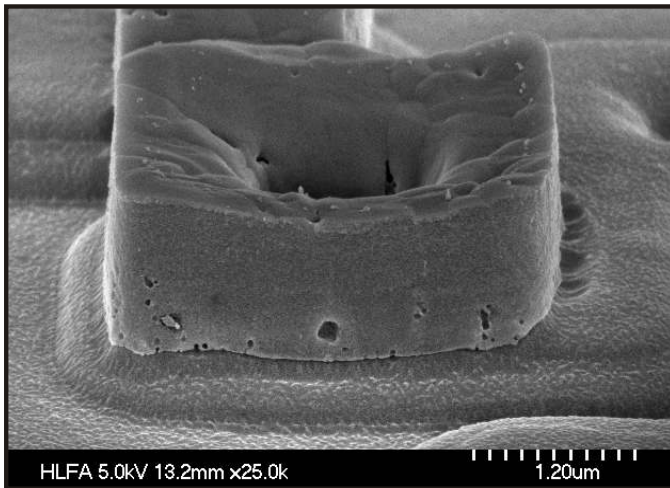


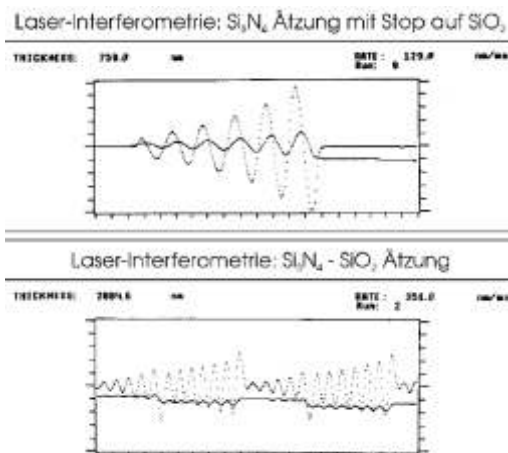
# Plasmalab Data

## Failure Analysis / Reverse Engineering



Courtesy of Infineon Munich:  
0.35 and 0.7  $\mu\text{m}$  techn  
etched to M1 - M2 - M3

**Equipment:**  
*Plasmalab 80 Plus*



### Results:

- Isotropic Si<sub>3</sub>N<sub>4</sub> removal with good selectivity to SiO<sub>2</sub> (and Al, Si)
- Anisotropic (or isotropic) Etch of SiO<sub>2</sub> with good selectivity to Si (and Al)
- Isotropic Al-Etch (or anisotropic)

### Technology:

- 13 MHz - Plasma
- Laser Interferometry
- Planar / Plasma Etch (PE)
- Reactive Ion Etch (RIE)